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C0603 [EIA CC0201]

MULTILAYER CERAMIC CHIP CAPACITORS



C Series High Q Capacitors

Type:

Issue date:

April 2011

TDK MLCC US Catalog

Version B11

MULTILAYER CERAMIC CHIP CAPACITORS

REMINDERS

Please read before using this product

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MULTILAYER CERAMIC CHIP CAPACITORS

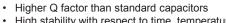


C Series High Q Capacitors

Type: C0603

Available Through Distribution Only*

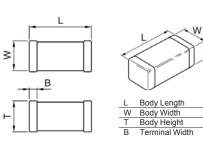
Features



- High stability with respect to time, temperature, frequency, and voltage
- Excellent attenuation
- High self-resonant frequency
- Lower power dissipation/less energy absorption
- Capacitance range of 0.2pF to 15pF
- Available in standard and tight tolerance
- Please contact TDK for Q values

Shape & Dimensions





Applications



150 J T XXXX

Internal Codes Packaging Style Packaging Code

Capacitance Tolerance Tolerance Code Tole

Т

W

B C D

E

G

.1

- High-frequency applications
- PA modules
- · Cellular communication, Bluetooth

OVE

- Cable/satellite TV
- GPS/satellite radio
- Filter networks/matching networks
- RF amplifiers/Low noise amplifiers

Style

Tape & Reel

Tolerance

± 0.05 pF

± 0.10 pF ± 0.25 pF ± 0.50 pF

± 0.20 pF

± 2% ± 5%

- VCOs, TCXOs, etc.
- DC blocking circuits



Part Number Construction

		C	0603	C0G	<u>1E</u>
Series Name -					
Dimensions L x	W (mm) –				
Case Code	Length	Width			
C0603	0.60 ± 0.03	0.30 ± 0.03			
Temperature Ch	aracteristic				
Temperature	Capacitance	Temperature			
Characteristics	Change	Range			
C0G	0±30 ppm/°C	-55 to +125°C			
Rated Voltage (I	DC)				
Voltage Code	Voltage (DC)				
1E	25V				
Nominal Capaci	tance (pF) –				

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

Capacitance Code	Capacitance
0R5	0.5pF
010	1pF
102	1,000pF (1nF)
105	1,000,000pF (1µF)

* This series is available through the distribution channel only. P	Please see <u>www.tdk.com/distributor.php</u> for a list of authorized distributors.
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MULTILAYER CERAMIC CHIP CAPACITORS



C0603 [EIA CC0201]

Capacitance Range Chart

Temperature Characteristics: C0G (0 ± 30ppm/°C) Rated Voltage: 25V(1E)

			Tolerance						
Capacitance (pF)	Cap Code	Temperature Characteristics	W B		С	D	Е	G	J
(pr)		Characteristics	(±0.05)	(±0.10pF)	(±0.25pF)	(±0.50pF)	(±0.20pF)	(±2%)	(±5%)
0.2	0R2	-55 to 125ºC,							
0.3	0R3	0±30 ppm/ºĆ							
0.4	0R4								
0.5	0R5								
0.6	0R6								
0.7	0R7	-							
0.8	OR8								
0.9	0R9								
1	010 1R1	-							
1.1	1R1								
1.2 1.3	1R2 1R3								
1.5	1R5								
1.6	1R6								
1.8	1R8								
2	020								
2.2	2R2								
2.4	2R4								
2.7	2R7								
3	030								
3.3	3R3								
3.6	3R6								
3.9	3R9								
4	040								
4.3	4R3								
4.7	4R7								
5	050								
5.1	5R1								
5.6	5R6								
6	060								
6.2 6.8	6R2 6R8	-							
<u> </u>	070								
7.5	7R5								
8	080								
8.2	8R2								
9	090								
9.1	9R1	1							
10	100	1							
11	110								
12	120								
13	130								
15	150								
16	160								
18	180								
20	200								

Standard Thickness

0.30 mm

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MULTILAYER CERAMIC CHIP CAPACITORS



Capacitance Range Table

C0603 [EIA CC0201]

Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0603C0G1E0R2WTQ	COG	25V	0.2	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R2BTQ	COG	25V	0.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R3WTQ	COG	25V	0.3	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R3BTQ	COG	25V	0.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R4WTQ	COG	25V	0.4	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R4BTQ	COG	25V	0.4	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R5WTQ	COG	25V	0.5	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R5BTQ	COG	25V	0.5	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R6WTQ	COG	25V	0.6	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R6BTQ	COG	25V	0.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R7WTQ	COG	25V	0.7	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R8WTQ	COG	25V	0.7	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R7BTQ	COG	25V	0.7	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R8BTQ	C0G	25V	0.8	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R9WTQ	COG	25V	0.9	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R9BTQ	COG	25V	0.9	± 0.10pF	0.30 ± 0.03
C0603C0G1E010BTQ	COG	25V	1.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E010CTQ	COG	25V	1.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R1BTQ	COG	25V	1.1	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R1CTQ	COG	25V	1.1	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R2BTQ	COG	25V	1.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R2CTQ	COG	25V	1.2	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R3BTQ	COG	25V	1.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R3CTQ	COG	25V	1.3	± 0.25pF	0.30 ± 0.03
CO603COG1E1R5BTQ	COG	25V	1.5	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R5CTQ	COG	25V	1.5	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R6BTQ	COG	25V	1.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R6CTQ	COG	25V	1.6	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R8BTQ	COG	25V	1.8	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R8CTQ	COG	25V	1.8	± 0.25pF	0.30 ± 0.03
C0603C0G1E020BTQ	COG	25V	2.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E020CTQ	COG	25V	2.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R2BTX	COG	25V	2.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R2CTX	COG	25V	2.2	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R4BTX	COG	25V	2.4	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R4CTX	COG	25V	2.4	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R7BTX	COG	25V	2.7	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R7CTX	COG	25V	2.7	± 0.25pF	0.30 ± 0.03
C0603C0G1E030BTX	COG	25V	3.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E030CTX	COG	25V	3.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E3R3BTX	COG	25V	3.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E3R3CTX	COG	25V	3.3	± 0.25pF	0.30 ± 0.03
C0603C0G1E3R6BTX	COG	25V	3.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E3R6CTX	COG	25V	3.6	± 0.25pF	0.30 ± 0.03

MULTILAYER CERAMIC CHIP CAPACITORS



Capacitance Range Table

C0603 [EIA CC0201]

Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

C0G C0G C0G C0G C0G C0G C0G C0G C0G C0G	25V 25V 25V 25V 25V 25V 25V 25V 25V 25V	3.9 3.9 4.0 4.0 4.3 4.3 4.3 4.7 4.7 5.0 5.0	± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF ± 0.25pF ± 0.25pF ± 0.25pF ± 0.10pF	$\begin{array}{c} 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \end{array}$
C0G C0G C0G C0G C0G C0G C0G C0G C0G C0G	25V 25V 25V 25V 25V 25V 25V 25V 25V 25V	4.0 4.0 4.3 4.3 4.7 4.7 5.0	± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF	$\begin{array}{c} 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \end{array}$
C0G C0G C0G C0G C0G C0G C0G C0G C0G C0G	25V 25V 25V 25V 25V 25V 25V 25V 25V 25V	4.0 4.3 4.3 4.7 4.7 5.0	± 0.25pF ± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF	$\begin{array}{c} 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \end{array}$
C0G C0G C0G C0G C0G C0G C0G C0G C0G C0G	25V 25V 25V 25V 25V 25V 25V 25V 25V	4.3 4.3 4.7 4.7 5.0	± 0.10pF ± 0.25pF ± 0.10pF ± 0.25pF	$\begin{array}{c} 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \\ 0.30 \pm 0.03 \end{array}$
C0G C0G C0G C0G C0G C0G C0G C0G C0G	25V 25V 25V 25V 25V 25V 25V	4.3 4.7 4.7 5.0	± 0.25pF ± 0.10pF ± 0.25pF	0.30 ± 0.03 0.30 ± 0.03
COG COG COG COG COG COG COG	25V 25V 25V 25V 25V 25V	4.7 4.7 5.0	± 0.10pF ± 0.25pF	0.30 ± 0.03
COG COG COG COG COG COG	25V 25V 25V 25V 25V	4.7 5.0	± 0.25pF	
COG COG COG COG COG	25V 25V 25V	5.0	· · ·	0.30 ± 0.03
COG COG COG COG	25V 25V		± 0.10pF	
C0G C0G C0G	25V	5.0		0.30 ± 0.03
C0G C0G			± 0.25pF	0.30 ± 0.03
COG		5.1	± 0.10pF	0.30 ± 0.03
	25V	5.1	± 0.25pF	0.30 ± 0.03
COG	25V	5.6	± 0.10pF	0.30 ± 0.03
	25V	5.6	± 0.25pF	0.30 ± 0.03
COG	25V	6.0	± 0.10pF	0.30 ± 0.03
C0G	25V	6.0	± 0.25pF	0.30 ± 0.03
COG	25V	6.2	± 0.10pF	0.30 ± 0.03
COG	25V	6.2	± 0.25pF	0.30 ± 0.03
COG	25V	6.8	± 0.10pF	0.30 ± 0.03
COG	25V	6.8	± 0.25pF	0.30 ± 0.03
COG	25V	7.0	± 0.10pF	0.30 ± 0.03
COG	25V	7.0	± 0.25pF	0.30 ± 0.03
COG	25V	7.5	± 0.10pF	0.30 ± 0.03
COG	25V	7.5	± 0.25pF	0.30 ± 0.03
COG	25V	8.0	± 0.10pF	0.30 ± 0.03
COG	25V	8.0	± 0.25pF	0.30 ± 0.03
COG	25V	8.2	± 0.10pF	0.30 ± 0.03
COG	25V	8.2	± 0.25pF	0.30 ± 0.03
COG	25V	9.0	± 0.10pF	0.30 ± 0.03
COG	25V	9.0	± 0.25pF	0.30 ± 0.03
COG	25V	9.1	± 0.10pF	0.30 ± 0.03
COG	25V	9.1	± 0.25pF	0.30 ± 0.03
COG	25V	10	± 0.20pF	0.30 ± 0.03
COG	25V	10	± 0.50pF	0.30 ± 0.03
COG	25V	11	± 2%	0.30 ± 0.03
COG	25V	11	± 5%	0.30 ± 0.03
COG	25V	12	± 2%	0.30 ± 0.03
COG	25V	12	± 5%	0.30 ± 0.03
COG	25V	13	± 2%	0.30 ± 0.03
COG	25V	13	± 5%	0.30 ± 0.03
COG	25V	15	± 2%	0.30 ± 0.03
COG	25V	15	± 5%	0.30 ± 0.03
000	25V	16	± 2%	0.30 ± 0.03
	C0G C0G C0G C0G C0G C0G C0G C0G C0G C0G	COG 25V COG	COG 25V 6.8 COG 25V 7.0 COG 25V 7.0 COG 25V 7.0 COG 25V 7.5 COG 25V 7.5 COG 25V 7.5 COG 25V 8.0 COG 25V 8.0 COG 25V 8.2 COG 25V 8.2 COG 25V 9.0 COG 25V 9.0 COG 25V 9.1 COG 25V 9.1 COG 25V 10 COG 25V 10 COG 25V 11 COG 25V 12 COG 25V 12 COG 25V 13 COG 25V 13 COG 25V 15 COG 25V 15	COG $25V$ 6.8 $\pm 0.10pF$ COG $25V$ 6.8 $\pm 0.25pF$ COG $25V$ 7.0 $\pm 0.10pF$ COG $25V$ 7.0 $\pm 0.25pF$ COG $25V$ 7.5 $\pm 0.10pF$ COG $25V$ 7.5 $\pm 0.25pF$ COG $25V$ 8.0 $\pm 0.10pF$ COG $25V$ 8.0 $\pm 0.25pF$ COG $25V$ 8.0 $\pm 0.25pF$ COG $25V$ 8.2 $\pm 0.25pF$ COG $25V$ 8.2 $\pm 0.25pF$ COG $25V$ 8.2 $\pm 0.25pF$ COG $25V$ 9.0 $\pm 0.25pF$ COG $25V$ 9.0 $\pm 0.25pF$ COG $25V$ 9.0 $\pm 0.25pF$ COG $25V$ 9.1 $\pm 0.25pF$ COG $25V$ 9.1 $\pm 0.25pF$ COG $25V$ 9.1 $\pm 0.25pF$ COG $25V$ 10 $\pm 0.25pF$ COG $25V$ 10 $\pm 0.25pF$ COG $25V$ 11 $\pm 2\%$ COG $25V$ 11 $\pm 2\%$ COG $25V$ 11 $\pm 2\%$ COG $25V$ 12 $\pm 2\%$ COG $25V$ 13 $\pm 2\%$ COG $25V$ 13 $\pm 2\%$ COG $25V$ 15 $\pm 2\%$

TDK MLCC US Catalog

MULTILAYER CERAMIC CHIP CAPACITORS



Capacitance Range Table

C0603 [EIA CC0201]

Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0603C0G1E180GTX	COG	25V	18	± 2%	0.30 ± 0.03
C0603C0G1E180JTX	COG	25V	18	± 5%	0.30 ± 0.03
C0603C0G1E200GTX	COG	25V	20	± 2%	0.30 ± 0.03
C0603C0G1E200JTX	COG	25V	20	± 5%	0.30 ± 0.03

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MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

C0603 Series – High Q Capacitors

No.	ltem	Performance		Test or Inspection Method				
1	External Appearance	No defects which may affect performance.		Inspect	Inspect with magnifying glass (10 $ imes$).			
2	Insulation Resistance	10,000MΩ min.		Apply ra	ted voltage for 60s.			
3	Voltage Proof	Withstand test volta insulation breakdow	Class Class 1 Above D	Apply voltage $3 \times$ rated voltageOC voltage shall be a	- - - applied for 1 to 5s. Charge			
					e current shall not e			
4	Capacitance	Within the specified	tolerance.	Class	Measuring Frequency	Measuring voltage		
				Class 1	1MHz±10%	0.5 - 5 V _{rms}		
5	Q	Rated Capacitance	Q	See No.	4 in this table for me	easuring condition.		
	(Class 1)	C ≥ 30pF	1,000 min.					
		C < 30pF 400 + 20×C min.						
		C : F	Rated capacitance (pF)					
6	Temperature	T.C. Tempera	Temperature coefficient shall be calculated based on					
	Characteristics	C0G 0 ± 30 pr	pm/ºC	values a	t 25°C and 85°C ten	nperature.		
	of Capacitance (Class 1)	Capacitance drift Within \pm 0.2% or \pm larger.	0.05pF, whichever	Measuring temperature below 20°C shall be -10°C and -25°C.				
7	Robustness of Terminations	No sign of termination breakage of ceramic signs.	on coming off, c, or other abnormal		ix 1) and apply a pus	on P.C. board (shown in shing force of 2N for Pushing force P.C. board		
8	Bending	No mechanical dam	No mechanical damage.		Reflow solder the capacitor on P.C. board (shown in Appendix 2) and bend it for 1mm. $50 \xrightarrow{20}{F}$			

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MULTILAYER CERAMIC CHIP CAPACITORS



C0603 Series – High Q Capacitors

No.	Item Performance			Test or Inspection Method				
9	Solderability	New solder to co termination.	ver ove	Completely soak both terminations in solder at $235\pm5^{\circ}$ C for 2 ± 0.5 s.				
		25% may have p	inholes	Solder: H63A (JIS Z 3282)				
		but not concentra	ated in	one spot.	Flux: Isopropyl alcohol (JIS K 8839)			
		Ceramic surface be exposed due termination mate	to melt		Rosin (JIS K 5902) 25% solid solution.			
			Ase	ection				
10	Resistance to so	older heat		Completely soak both terminations in solder at				
	External	No cracks are all	owed a	and terminations	$260\pm5^{\circ}$ C for 5 ± 1 s.			
	appearance shall be covered at least 60% with				Preheating condition			
		solder.			Temp.: 150±10°C			
	Capacitance	Characteristics		ige from the	Time: 1 to 2min.			
		Class 1 C0G		e before test	Flux: Isopropyl alcohol (JIS K 8839)			
				5% or ± 0.25 pF,	Rosin (JIS K 5902) 25% solid solution.			
			which	never larger.	Solder: H63A (JIS Z 3282)			
	Q (Class 1) Rated Capacitance		nce	Q	Leave the capacitor in ambient conditions for 6 to 24h			
		C ≥ 30pF		1,000 min.	before measurement.			
		C < 30pF 400 + 20×C min.		400 + 20×C min.				
		C	C : Rate	d capacitance (pF)	_			
	Insulation Resistance	Meet the initial sp	pec.					
	Voltage Proof	No insulation bre damage.	akdow	n or other	-			
11	Vibration				Reflow solder the capacitor on P.C. board (shown in			
	External appearance	No mechanical d	amage	2.	Appendix 1) before testing. Vibrate the capacitor with amplitude of 1.5mm P-P			
	Capacitance	Characteristics		ige from the before test	 sweeping the frequencies from 10Hz to 55Hz and back to 10Hz after 1min. 			
		Class 1 C0G	±2.5	citance drift within 5% or \pm 0.25pF, never larger.	Repeat this for 2h each in 3 perpendicular directions.			
	Q (Class 1)	Rated Capacitar	nce	Q	-			
		C ≥ 30pF		1,000 min.				
					-			

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MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

C0603 Series – High Q Capacitors

No.	ltem		Test or	Inspection Method					
12	Temperature cy External appearance	r cle No mechanical d	ama	ge.	Reflow solder the capacitors on a P.C. board (shown i Appendix 1) before testing. Expose the capacitor in the conditions in step 1				
	Capacitance	Characteristics Class 1 C0G	va Ca	ange from the lue before test pacitance drift within 2.5% or ± 0.25 pF,	 through step 4, and repeat 5 times consecutively. Leave the capacitor in ambient conditions for 6 to 2 before measurement. 				
				ichever larger.	Step	Temperature (°C)	Time (min.)		
					- 1	Min. operating temp. ± 3	30 ± 3		
	Q (Class 1)	Rated Capacitan	ice	Q	2	Reference Temp.	2-5		
		C ≥ 30pF	1,000 min.		3	Max. operating temp. \pm 2	30 ± 2		
		C < 30pF		400 + 20×C min.	4	Reference Temp.	2 - 5		
		C : Rated capacitance (pF)							
	Resistance Voltage Proof	No insulation bre damage.	akdo	own or other	-				
13	Moisture Resistance (Steady State) External No mechanical damage. appearance			Reflow solder the capacitor on P.C. board (shown in Appendix 1) before testing. Leave at temperature 40±2°C, 90 to 95%RH for 500					
	Capacitance	Characteristics		ange from the lue before test	 +24,0h. Leave the second second	ne capacitor in ambient con	dition for 6 to 24h		
		Class 1 COG	± {	pacitance drift within 5% or \pm 0.5pF, ichever larger.	before r	neasurement.			
	Q (Class 1)	Rated Capacitan	се	Q	-				
	· · · ·	C ≥ 30pF	-	350 min.					
		10pF ≤ C < 30pF		275 + 5/2×C min.					
		C < 10pF	200 + 10×C min.						
			: Ra	ated capacitance (pF)					
	Insulation Resistance	1,000MΩ min.		, vr /	-				

MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

C0603 Series – High Q Capacitors

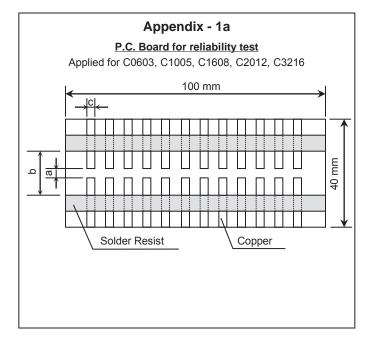
No.	ltem	Perform	ance			Test or Inspection Method			
14	Moisture Resist	ance			Reflow solder the capacitors on P.C. board (shown in Appendix 1) before testing.				
	External	No mechanical damage.							
	appearance					Apply the rated voltage at temperature $40\pm2^{\circ}$ C and - to 95%RH for 500 +24.0h.			
	Capacitance	Characte	eristics		ange from the lue before test	Charge/discharge current shall not exceed 50mA.			
		Class 1	C0G	Capacitance drift within \pm 7.5% or \pm 0.75pF, whichever larger.		Leave the capacitor in ambient conditions for 6 to 24h before measurement.			
				1		Use this measurement for initial value.			
	Q (Class 1)	Rated C	•	се	Q				
		C ≥ 30pl			200 min.				
		C < 30pl	=		100 + 10/3×C min.				
			C	: Ra	ated capacitance (pF)				
	Insulation Resistance	500MΩ n	nin.						
5	Life					Reflow solder the capacitor on P.C. board (shown in			
	External appearance	No mech	anical d	ama	ge.	Appendix 1) before testing. Apply 2x rated voltage at 125±2°C for 1,000 +48, 0h.			
	Capacitance				ange from the lue before test	Charge/discharge current shall not exceed 50mA.			
		Class 1	C0G	Ca	pacitance drift within 3% or $\pm 0.3pF$,	Leave the capacitors in ambient condition for 6 to 24h before measurement.			
					ichever larger.	Use this measurement for initial value.			
	Q (Class 1)	Rated Ca	apacitan	се	Q				
		C ≥ 30pF	:		350 min.				
		10pF ≤ 0	; < 30pF		275 + 5/2×C min.				
		C < 10pF	:		200 + 10×C min.				
			C	: Ra	ated capacitance (pF)				
	Insulation Resistance	1,000MΩ min.							

MULTILAYER CERAMIC CHIP CAPACITORS



General Specifications

C0603 Series – High Q Capacitors



P.C. Board for bending test Applied for C0603, C1005

Appendix - 2a

Material : Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness :	Appendix - 2	0.8mm
	Appendix - 1	1.6mm



Copper (thickness 0.035mm)

Case Code		Dimensions (mm)		m)
JIS	EIA	а	b	С
C0603	CC0201	0.3	0.8	0.3

* This series is available through the distribution channel only. Please see www.tdk.com/distributor.php for a list of authorized distributors.

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MULTILAYER CERAMIC CHIP CAPACITORS



С

В

Reflow Soldering

A B

С

Symbol

Recommended Soldering Land Pattern

Chip capacitor

А

Solder land

Unit: mm

C0603

[CC0201]

0.25 ~ 0.35

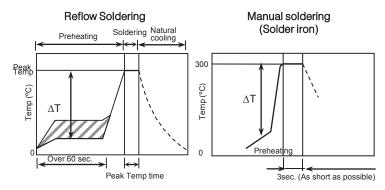
0.2 ~ 0.3

0.25 ~ 0.35

Solder resist

C0603 Series – High Q Capacitors

Recommended Soldering Profile



Recommended soldering duration

Temp./	Reflow Soldering		
Dura.	Peak temp	Duration	
Solder	(°C)	(sec.)	
Sn-Pb Solder	230 max.	20 max.	
Lead-Free Solder	260 max.	10 max.	

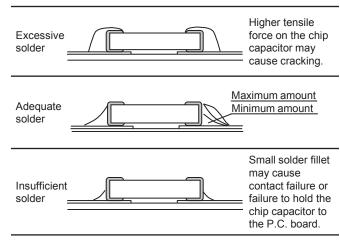
Recommended solder compositions Sn-37Pb (Sn-Pb solder) Sn-3.0Ag-0.5Cu (Lead Free Solder)

Preheating Condition

Soldering	Temp. (ºC)
Reflow soldering	∆T ≤ 150
Manual soldering	∆T ≤ 150

Recommended Solder Amount

Туре



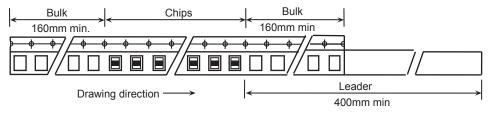
MULTILAYER CERAMIC CHIP CAPACITORS



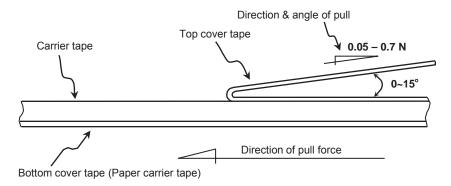
Packaging Information

C0603 Series – High Q Capacitors

• Carrier Tape Configuration



• Peel Back Force (Top Tape)



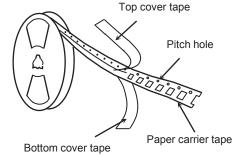
· Chip Quantity Per Reel and Structure of Reel

• Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

 \bullet The missing of components shall be less than 0.1%

Components shall not stick to the cover tape.

• The cover tape shall not protrude beyond the edges of the carrier tape and shall not cover the sprocket holes.



Paper Carrier Tape & Reel

(Bottom cover tape is not always applied)

Case	Code	Chip	Taning	Chip quantity (pcs.)	
JIS	EIA	Thickness (mm)	Taping Material	φ178mm (7") reel	
C0603	CC0201	0.30	Paper	15,000	

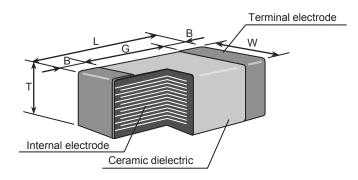
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MULTILAYER CERAMIC CHIP CAPACITORS



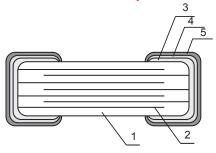
C0603 Series – High Q Capacitors

• Shape & Dimensions



Case Code		Dimensions (mm)				
JIS	EIA	L	W	Т	В	G
C0603	CC0201	0.60	0.30	0.30	0.15	0.20 min.

• Inside Structure & Material System



No.	NAME	MATERIAL
		Class 1
(1)	Ceramic Dielectric	CaZrO ₃
(2)	Internal Electrode	Nickel (Ni)
(3)		Copper (Cu)
(4)	Termination	Nickel (Ni)
(5)		Tin (Sn)

Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

- Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- For REACH (SVHC : 15 substances according to ECHA / October 2008) : All TDK MLCC do not contain these 15 substances.
- For European Directive 2000/53/CE and 2005/673/CE : Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.
- For European Directive 2003/11/CE : Pentabromodiphenylether, Octabromodiphenyl-ether are not contained in all TDK MLCC.